

APFA2507R3G3C-CC

2.5 x 0.7 mm Right Angle SMD Chip LED Lamp



DESCRIPTIONS

- The Hyper Red device is based on light emitting diode chip made from AlGaInP
- The Green source color devices are made with InGaN on Sapphire Light Emitting Diode
- Electrostatic discharge and power surge could damage the LEDs
- It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs
- All devices, equipments and machineries must be electrically grounded

FEATURES

- 2.5 x 1.0 x 0.7 mm right angle SMD LED, 0.7 mm thickness
- Low power consumption
- Wide viewing angle
- Ideal for backlight and indicator
- Package: 3000 pcs / reel
- Moisture sensitivity level: 3
- Tinned pads for improved solderability
- Halogen-free
- RoHS compliant

APPLICATIONS

- Backlight
- Status indicator
- Home and smart appliances
- Wearable and portable devices
- Healthcare applications

ATTENTION

Observe precautions for handling electrostatic discharge sensitive devices

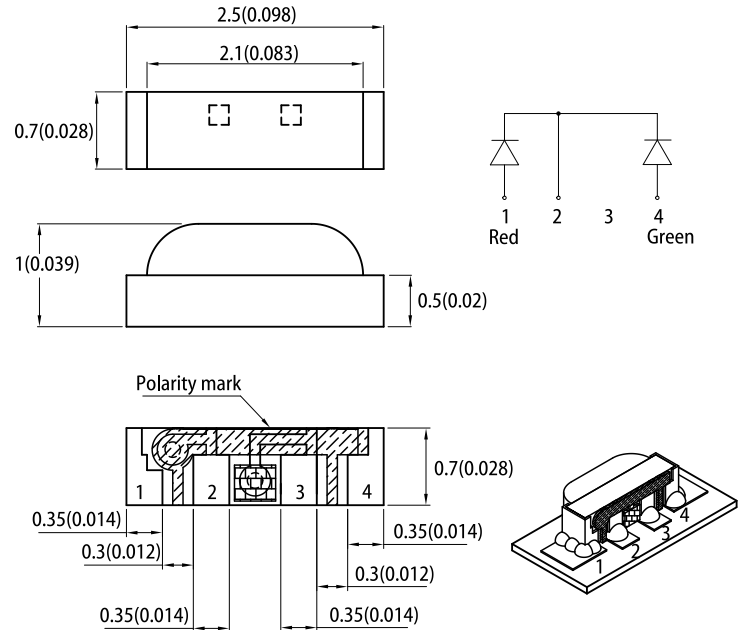


SELECTION GUIDE

Part Number	Emitting Color (Material)	Lens Type	Iv (mcd) @ 20mA ^[2]		Viewing Angle ^[1]
			Min.	Typ.	2θ1/2
APFA2507R3G3C-CC	■ Hyper Red (AlGaInP)	Water Clear	500	800	130°
			*200	*400	
	■ Green (InGaN)		400	550	
			*400	*550	

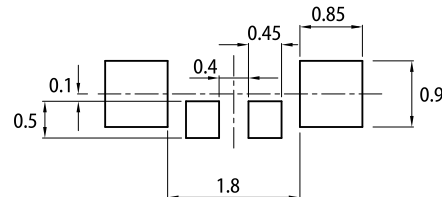
Notes:
 1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
 2. Luminous intensity / luminous flux: +/-15%.
 * Luminous intensity value is traceable to CIE127-2007 standards.

PACKAGE DIMENSIONS



RECOMMENDED SOLDERING PATTERN

(units : mm; tolerance : ± 0.1)



Notes:
 1. All dimensions are in millimeters (inches).
 2. Tolerance is ±0.15(0.006") unless otherwise noted.
 3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
 4. The device has a single mounting surface. The device must be mounted according to the specifications.
 5. For right angle SMD LEDs, the solder stencil should be at least 5mil in thickness, to prevent poor solder wetting due to insufficient solder paste.

ELECTRICAL / OPTICAL CHARACTERISTICS at T_A=25°C

Parameter	Symbol	Emitting Color	Value		Unit
			Typ.	Max.	
Wavelength at Peak Emission I _F = 20mA	λ_{peak}	Hyper Red Green	640 515	-	nm
Dominant Wavelength I _F = 20mA	λ_{dom} ^[1]	Hyper Red Green	625 525	-	nm
Spectral Bandwidth at 50% Φ REL MAX I _F = 20mA	$\Delta\lambda$	Hyper Red Green	20 35	-	nm
Forward Voltage I _F = 20mA	V _F ^[2]	Hyper Red Green	2.2 3.3	2.8 4.1	V
Reverse Current (V _R = 5V)	I _R	Hyper Red Green	-	10 50	μA
Temperature Coefficient of λ_{peak} I _F = 20mA, -10°C ≤ T ≤ 85°C	TC _{λ_{peak}}	Hyper Red Green	0.13 0.05	-	nm/°C
Temperature Coefficient of λ_{dom} I _F = 20mA, -10°C ≤ T ≤ 85°C	TC _{λ_{dom}}	Hyper Red Green	0.06 0.03	-	nm/°C
Temperature Coefficient of V _F I _F = 20mA, -10°C ≤ T ≤ 85°C	TC _V	Hyper Red Green	-2.0 -3.0	-	mV/°C

Notes:

1. The dominant wavelength (λ_d) above is the setup value of the sorting machine. (Tolerance λ_d : ±1nm.)
2. Forward voltage: ±0.1V.
3. Wavelength value is traceable to CIE127-2007 standards.
4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

ABSOLUTE MAXIMUM RATINGS at T_A=25°C

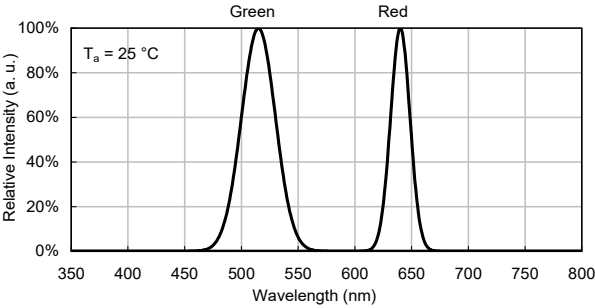
Parameter	Symbol	Value		Unit
		Hyper Red	Green	
Power Dissipation	P _D	84	102.5	mW
Reverse Voltage	V _R	5	5	V
Junction Temperature	T _J	115	115	°C
Operating Temperature	T _{op}	-40 To +85		°C
Storage Temperature	T _{stg}	-40 To +85		°C
DC Forward Current	I _F	30	25	mA
Peak Forward Current	I _{FP} ^[1]	150	150	mA
Electrostatic Discharge Threshold (HBM)	-	3000	450	V
Thermal Resistance (Junction / Ambient)	R _{th JA} ^[2]	520	750	°C/W
Thermal Resistance (Junction / Solder point)	R _{th JS} ^[2]	380	610	°C/W

Notes:

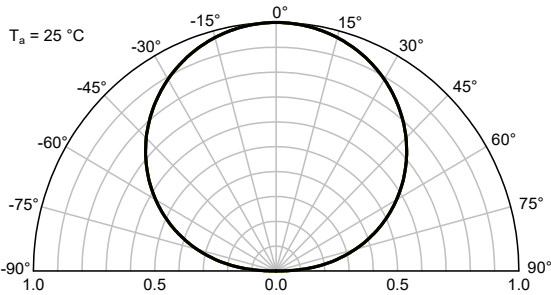
1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. R_{th JA}, R_{th JS} Results from mounting on PC board FR4 (pad size ≥ 16 mm² per pad).
3. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

TECHNICAL DATA

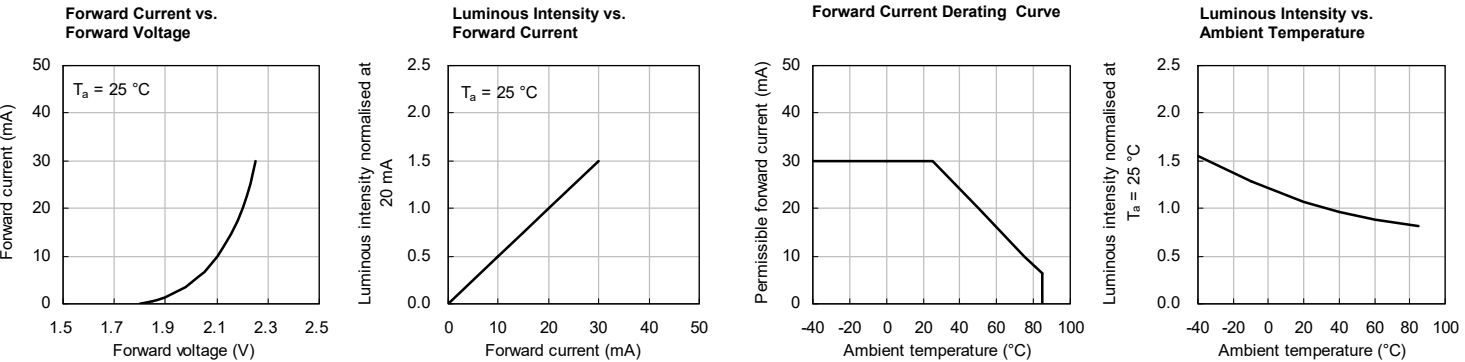
RELATIVE INTENSITY vs. WAVELENGTH



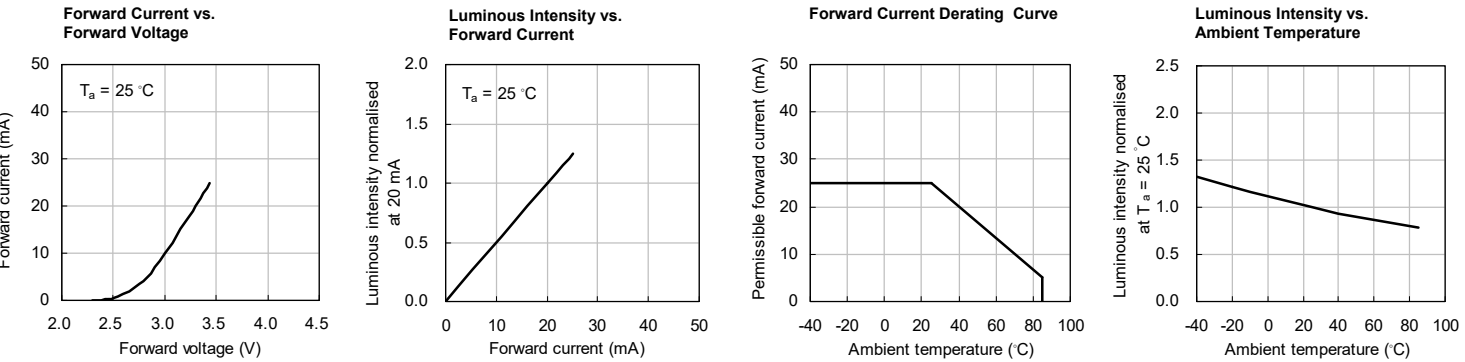
SPATIAL DISTRIBUTION



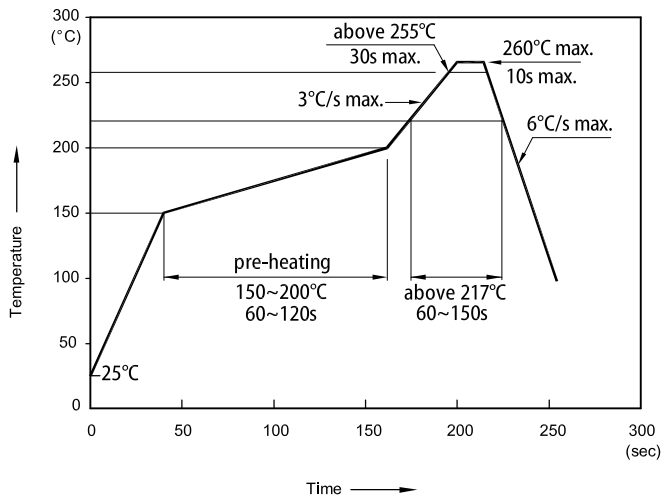
HYPER RED



GREEN



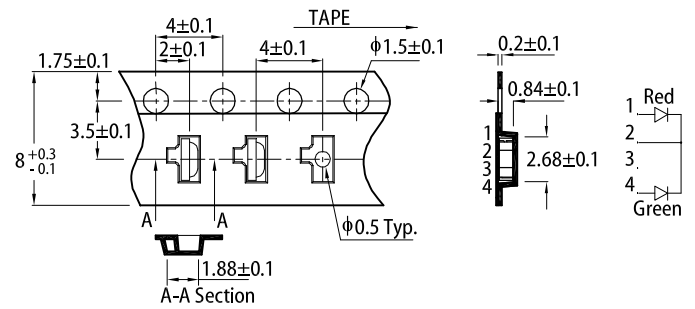
REFLOW SOLDERING PROFILE for LEAD-FREE SMD PROCESS



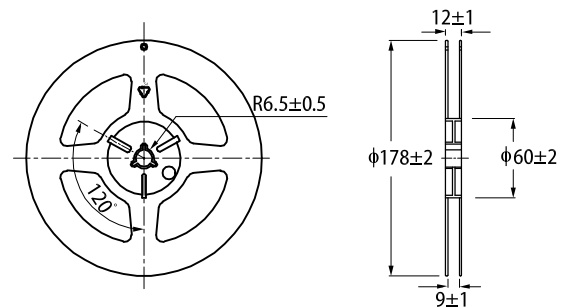
Notes:

1. Don't cause stress to the LEDs while it is exposed to high temperature.
2. The maximum number of reflow soldering passes is 2 times.
3. Reflow soldering is recommended. Other soldering methods are not recommended as they might cause damage to the product.

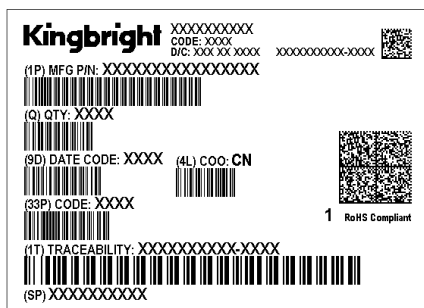
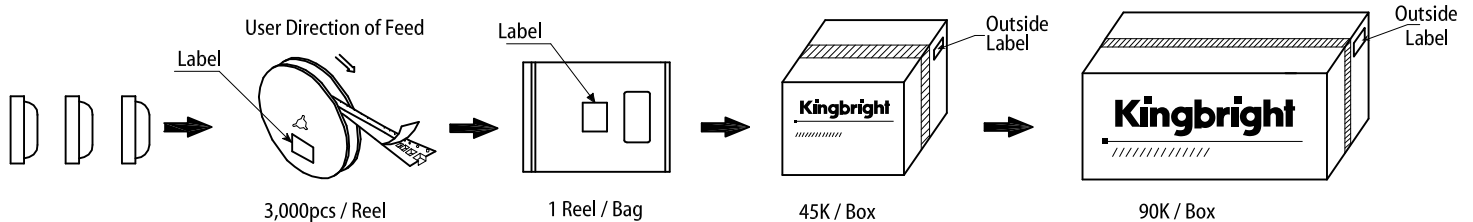
TAPE SPECIFICATIONS (units : mm)



REEL DIMENSION (units : mm)



PACKING & LABEL SPECIFICATIONS



PRECAUTIONARY NOTES

1. The information included in this document reflects representative usage scenarios and is intended for technical reference only.
2. The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
3. When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If customer usage exceeds the specified limits, Kingbright will not be responsible for any subsequent issues.
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